## **CLAIMS**

* * **		•			
Wha	ıt 1S	cla	ıme	:d 15	٠.

- 1 1. An optical light guide apparatus comprising:
- 2 a connector;
- a bundle of optical fibers positioned within said connector; and
- an epoxy joining said optical fibers together,
- wherein said bundle of optical fibers has a polished distal end at one end of said
- 6 connector, and
- wherein the ratio of fiber size to binder particulate size of said epoxy is sufficient
- 8 to maintain the integrity of said bundle of optical fibers during polishing of said distal
- 9 end.
- 1 2. The apparatus in claim 1, wherein the ratio of fiber size to binder particulate size
- of said epoxy is above 25.
- 1 3. The apparatus in claim 1, wherein the ratio of fiber size to binder particulate size
- of said epoxy is between approximately 25 and 50.
- 1 4. The apparatus in claim 1, wherein said connector is adapted to extend through an
- 2 opening in a surface of a device, such that said distal end of said bundle of optical fibers
- one of is recessed in, is substantially flush with, and extends from a surface of said device
- 4 through which said connector extends.
- 1 5. The apparatus in claim 1, further comprising a protective sheath surrounding a
- 2 portion of said bundle of fibers that extend outward from said connector.

- 1 6. The apparatus in claim 5, further comprising a second connector, wherein said
- 2 connector is positioned at a first end of said protective sheath and said second connector
- 3 is positioned at a second end of said protective sheath that is opposite said first end of
- 4 said protective sheath.
- 1 7. The apparatus in claim 1, wherein said optical fibers comprise one of a glass and
- 2 quartz.
- 1 8. An optical light guide apparatus comprising:
- 2 a protective sheath;
- a connector connected to an end of said protective sheath;
- a bundle of optical fibers positioned within said protective sheath and within said
- 5 connector; and
- an epoxy joining said optical fibers together,
- wherein the coefficient of thermal expansion of said epoxy matches that of said
- 8 connector.
- 1 9. The apparatus in claim 8, wherein said connector is adapted to extend through an
- opening in a surface of a device, such that said distal end of said bundle of optical fibers
- 3 one of is recessed in, is substantially flush with, and extends from a surface of said device
- 4 through which said connector extends.
- 1 10. The apparatus in claim 9, further comprising a seal on said connector.
- 1 11. The apparatus in claim 10, wherein said seal seals said opening.
- 1 12. The apparatus in claim 9, wherein said connector further comprises a threaded
- 2 jam nut adapted to engage threads in said opening.

- 1 13. The apparatus in claim 8, further comprising a second connector, wherein said
- 2 connector is positioned at a first end of said protective sheath and said second connector
- 3 is positioned at a second end of said protective sheath that is opposite said first end of
- 4 said protective sheath.
- 1 14. The apparatus in claim 8, wherein said optical fibers comprise one of a glass and
- 2 quartz.
- 1 15. A method of forming an optical light guide apparatus, said method comprising:
- bonding a bundle of optical fibers together using an epoxy;
- polishing a distal end of said bundle of optical fibers to create an optical aperture,
- 4 wherein the ratio of fiber size to binder particulate size of said epoxy used in said
- 5 bonding process is sufficient to maintain the integrity of said bundle of optical fibers
- 6 during said polishing of said distal end; and
- 7 positioning said bundle of optical fibers into a protective sheath and a connector,
- wherein said connector is positioned at one end of said protective sheath, and
- wherein said distal end of said bundle of optical fibers is positioned at an end of
- 10 said connector.
- 1 16. The method in claim 15, wherein the ratio of fiber size to binder particulate size
- of said epoxy used in said bonding process is above 25.
- 1 17. The apparatus in claim 15, wherein the ratio of fiber size to binder particulate size
- of said epoxy used in said bonding process is between approximately 25 and 50.
- 1 18. The method in claim 15, further comprising extending said connector through an
- 2 opening in a surface of a device, such that said distal end of said bundle of optical fibers

- 3 one of is recessed in, is substantially flush with, and extends from a surface of said device
- 4 through which said connector extends.
- 1 19. The method in claim 18, further comprising positioning, on said connector, a
- 2 threaded jam nut adapted to engage threads in said opening.
  - 20. The method in claim 18, further comprising positioning a seal on said connector, wherein said seal seals said opening.